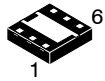


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

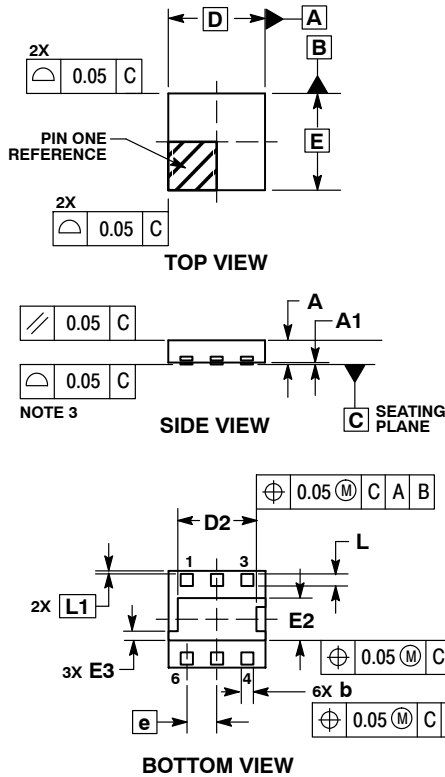
ON Semiconductor®



SCALE 4:1

XDFN6 1.6x1.6, 0.5P
CASE 711AC-01
ISSUE O

DATE 21 OCT 2010



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.60 BSC	
D2	1.25	1.35
E	1.60 BSC	
E2	0.65	0.75
E3	0.15 REF	
e	0.50 BSC	
L	0.15	0.25
L1	0.05 BSC	

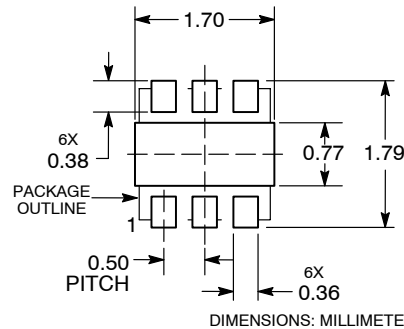
GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
MM = Date Code

(Note: Microdot may be in either location)
*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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